



| | # | Layer | Thickness | Description | Dk | Df | Note |
|---|---|---------------|-----------|---|-----|-------|-----------------------------|
| | | | | | | | |
|  | | Top Solder | 0.015mm | Soldermask IPC-SM840 | 3,5 | 0,028 | used on rigid parts |
| | 1 | Top Side | 0.030mm | Starting foil 1/4oz. after plating and processing | | | |
| | | | 0.065mm | Prepreg IPC-4101/127/128 | 3,5 | 0,011 | FR-4.1 filled, halogen free |
| | 2 | Inner Layer 1 | 0.035mm | ED Base Copper | | | |
| | | | 0.200mm | Core IPC-4101/127/128 | 4,4 | 0,011 | FR-4.1 filled, halogen free |
| | 3 | Inner Layer 2 | 0.035mm | ED Base Copper | | | |
| | | | 0.125mm | Prepreg IPC-4101/127/128 | 3,7 | 0,011 | FR-4.1 filled, halogen free |
| | 4 | Inner Layer 3 | 0.035mm | ED Base Copper | | | |
| | | | 0.200mm | Core IPC-4101/127/128 | 4,4 | 0,011 | FR-4.1 filled, halogen free |
| | 5 | Inner Layer 4 | 0.035mm | ED Base Copper | | | |
| | | | 0.065mm | Prepreg IPC-4101/127/128 | 3,5 | 0,011 | FR-4.1 filled, halogen free |
| | 6 | Bottom Side | 0.030mm | Starting foil 1/4oz. after plating and processing | | | |
| | | Bottom Solder | 0.015mm | Soldermask IPC-SM840 | 3,5 | 0,028 | used on rigid parts |
| Total thickness: 0.885mm | | | | | | | |

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|---|--|--|----------|---------------|---|
| | HDI6_1-4-1_0,89_35_V2.12 | | | |  |
| notes: | PCB Thickness Tolerance: ± 10% | | | | |
| | customer | | created | | |
| Final copper thickness according to IPC-6012 | pcb name | | approved | | |
| | engineer | | format | A4, landscape | |
| Please regard to our sectional design rules: ► www.we-online.com | date | | | | |
| | Template Revision: 02/2021 by Andreas Schilpp / Michael Kress / Werner Öchslen | | | | |